

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-8. (Canceled)

9. (Currently Amended) A method of manufacturing a bump structure, comprising:

forming a liquid-repelling part with a liquid-repelling characteristic for droplets and a liquid-attracting part that is more wettable than the liquid-repelling part for the droplets on an upper surface of an insulating layer, the droplets including a precursor of UV-hardening resin;

discharging the droplets onto the liquid-attracting part to form a protruding part precursor;

hardening the protruding part precursor by applying ~~energy~~ UV rays to form a protruding part; and

forming a conductive layer so as to cover the protruding part.

10-13. (Canceled)

14. (Original) The method of manufacturing a bump structure according to Claim 9, before the protruding part precursor is formed, a liquid repelling treatment being carried out on a region adjacent to a region in which the protruding part precursor is formed.

15. (Original) The method of manufacturing a bump structure according to Claim 9, the droplets being discharged using an ink jet method.

16-20. (Canceled)

21. (New) The method of manufacturing a bump structure according to claim 9, discharging the droplets comprising discharging the droplets on the insulating layer.

22. (New) The method of manufacturing a bump structure according to claim 21, forming the conductive layer comprising sandwiching the protruding part between the conductive layer and the insulating layer on which the droplets are discharged.